



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Alfred Kersch
Filed : Concurrently herewith
Title : Reaction Chamber for Processing a Substrate Wafer, and Method for Operating the Chamber

INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

German Published, Non-Prosecuted Patent Application No. DE 197 47 164 A1 (Kersch et al.), dated May 6, 1999, configuration for processing a substrate wafer and method for its operation.

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications, patents and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "W. Stemer", written over a horizontal line.

For Applicant

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